
**UNITED STATES
SECURITIES AND EXCHANGE COMMISSION
WASHINGTON, D.C. 20549**

FORM 8-K

**CURRENT REPORT
Pursuant to Section 13 or 15(d)
of the Securities Exchange Act of 1934**

Date of Report (Date of earliest event reported): October 12, 2026

TTM TECHNOLOGIES, INC.

(Exact name of Registrant as specified in its charter)

Delaware
(State of
Incorporation)

000-31285
(Commission
File Number)

91-1033443
(I.R.S. Employer
Identification No.)

**200 East Sandpointe, Suite 400
Santa Ana, California**
(Address of principal executive offices)

92707
(Zip Code)

(714) 327-3000
Registrant's telephone number, including area code

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

- ☐ Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
- ☐ Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
- ☐ Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
- ☐ Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))

Securities registered pursuant to Section 12(b) of the Act:

Title of each class	Trading Symbol(s)	Name of each exchange on which registered
Common Stock, \$0.001 par value	TTMI	Nasdaq Global Select Market

Indicate by check mark whether the registrant is an emerging growth company as defined in Rule 405 of the Securities Act of 1933 (§230.405 of this chapter) or Rule 12b-2 of the Securities Exchange Act of 1934 (§240.12b-2 of this chapter).

Emerging growth company ☐

If an emerging growth company, indicate by check mark if the registrant has elected not to use the extended transition period for complying with any new or revised financial accounting standards provided pursuant to Section 13(a) of the Exchange Act. ☐

Section 7 - Regulation FD

Item 7.01 – Regulation FD Disclosure.

On October 12, 2026, TTM Technologies, Inc. (the “Company”) issued a press release announcing plans to invest an additional \$400 million to expand manufacturing capacity across four facilities in China and its facility in Penang, Malaysia, to support growing demand for artificial intelligence infrastructure. The additional investment is incremental to the Company’s previously disclosed commitment to invest \$1.2 billion during the 2025 to 2029 period.

A copy of the press release is furnished with this Current Report on Form 8-K as Exhibit 99.1 and is incorporated herein by reference.

The information furnished in this Item 7.01, including Exhibit 99.1, shall not be deemed to be “filed” for the purposes of Section 18 of the Securities Exchange Act of 1934, as amended (the “Exchange Act”), or otherwise subject to the liabilities of that section, and shall not be incorporated by reference into any registration statement or other document filed under the Securities Act of 1933, as amended, or the Exchange Act, except as shall be expressly set forth by specific reference in such filing.

Cautionary Note Regarding Forward-Looking Statements

This Report, including Exhibit 99.1, contains forward-looking statements that relate to future events. The Company cautions you that such statements are simply predictions and actual events or results may differ materially. These statements reflect the Company’s current expectations, and the Company does not undertake to update or revise these forward-looking statements, even if experience or future changes make it clear that any projected results expressed or implied in this or other Company statements will not be realized. The statements also involve risks and uncertainties, many of which are beyond the Company’s control, which could cause actual results to differ materially from the forward-looking statements. For a description of additional factors that may cause the Company’s actual events or results to differ from any forward-looking statements, please review the information set forth in the “Risk Factors” and “Management’s Discussion and Analysis of Financial Condition and Results of Operations” sections of the Company’s public reports filed with the Securities and Exchange Commission.

Item 9.01. Financial Statements and Exhibits

(d) Exhibits

The following exhibits are filed with this Report:

<u>Exhibit Number</u>	<u>Description</u>
99.1	Press Release dated October 12, 2026.
104	Cover Page Interactive Data File (embedded within the Inline XBRL document)

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this Report to be signed on its behalf by the undersigned hereunto duly authorized.

TTM TECHNOLOGIES, INC.

Date: October 13, 2026

/s/ Daniel J. Weber

By: Daniel J. Weber

Executive Vice President, Chief Legal Officer & Secretary

**TTM Technologies Announces \$400 Million in Planned Strategic Investments to Accelerate AI Infrastructure Capacity in China and Malaysia**

CEO Edwin Roks and COO Jim Walsh unveil “Rapid-Ramp” brownfield capacity expansion to aggressively scale advanced N+M interconnect technology for AI Data Center Infrastructure, Hyperscalers and Networking Customers.

SANTA ANA, Calif. — October 12, 2026 — TTM Technologies, Inc. (NASDAQ: TTMI) (“TTM”), a leading global manufacturer of technology products, including mission systems, radio frequency (“RF”) components, RF microwave/microelectronic assemblies, and technologically advanced interconnect products, including printed circuit boards (“PCBs”) and substrates, announced today a \$400 million investment plan to expand capacity across four key facilities in China and its strategic southeast Asia plant in Penang, Malaysia. This expansion initiative represents incremental investments to the previously disclosed commitment to invest \$1.2 billion through the 2025-2029 timeframe and is buttressed by ongoing discussions with our long-standing customer partners indicating expected demand increases.

The planned investments are dedicated to supporting the surge in Artificial Intelligence (“AI”) infrastructure demand, primarily scaling TTM’s advanced N+M asymmetrical, interconnect manufacturing technology products. This expansion underscores TTM’s commitment to its shareholders to capitalize on aggressive organic growth opportunities within the AI sector, with the goal of ensuring the company’s customers have access to both the critical capacity and innovative capabilities of TTM’s advanced interconnect technologies. To meet the urgent needs of data center infrastructure providers, hyperscalers, and networking customers, TTM is bypassing more time-consuming “greenfield” construction approaches in favor of its brownfield approach for strategic expansions. This “rapid ramp” approach entails optimizing existing operational space and integrating cutting-edge equipment to bring AI-specific PCB production capacity online very efficiently.

“The AI boom has increasingly placed significant demands for capacity within the AI hardware supply chain. TTM anticipates this market to remain highly dynamic and we will continue to work closely with our customers to define additional expansions as required. The rapid growth in demand requires us to make rapid capacity increases across several of our facilities,” said Edwin Roks, President and CEO of TTM. “By leveraging our existing footprint in China and Penang to scale our advanced technology, we believe we are shortening the time between investment and revenue such that our customers can scale without unnecessary or prohibitive bottlenecks,” said Jim Walsh, Chief Operating Officer of TTM. This expansion reinforces TTM’s position as a critical interconnect and integration partner for the AI revolution, providing the high-performance hardware that enables the world’s most powerful computing systems.

TTMI expects to provide additional commentary for investors during its Third Quarter 2026 Earnings Conference call, with the specific date and time to be announced in coming weeks.



About TTM

TTM Technologies, Inc. is a leading global manufacturer of technology products, including mission systems, RF components, RF microwave/microelectronic assemblies, and technologically advanced interconnect products, including PCBs and substrates. TTM stands for time-to-market, representing how TTM's time-critical, one-stop design, engineering and manufacturing services enable customers to reduce the time required to develop new products and bring them to market. Additional information can be found at www.ttm.com.

Forward-Looking Statements

This release contains forward-looking statements that relate to future events or performance. TTM cautions you that such statements are simply predictions and actual events or results may differ materially. These statements reflect TTM's current expectations, and TTM does not undertake to update or revise these forward-looking statements, even if experience or future changes make it clear that any projected results expressed or implied in this or other TTM statements will not be realized. Further, these statements involve risks and uncertainties, many of which are beyond TTM's control, which could cause actual results to differ materially from the forward-looking statements. These risks and uncertainties include, but are not limited to, the execution and implementation of TTM's investment plan, general market and economic conditions, including interest rates, currency exchange rates, and consumer spending, demand for TTM's products, market pressures on prices of TTM's products, warranty claims, changes in product mix, contemplated significant capital expenditures and related financing requirements, TTM's dependence upon a small number of customers, and other factors set forth in the "Risk Factors" and "Management's Discussion and Analysis of Financial Condition and Results of Operations" sections of TTM's public reports filed with the SEC.

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